Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.025”**

**‘”**

**.025”**

**.015”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .015” X .015”**

**Backside Potential: Cathode**

**Mask Ref: ZCB**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 11/8/21**

**MFG: SPRAGUE-ALLEGRO THICKNESS .007” P/N: THZ010A05**

**DG 10.1.2**

#### Rev B, 7/19/02